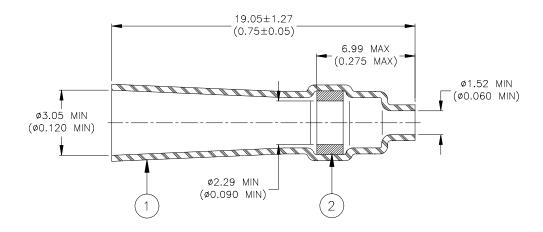
## SPECIFICATION CONTROL DRAWING



## **MATERIALS**

- 1. INSULATION SLEEVE: Heat shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- 2. SOLDER PREFORM WITH FLUX:

SOLDER: TYPE Sn63 per ANSI J-STD-006.

FLUX: TYPE ROL1 per ANSI J-STD-004.

## **APPLICATION**

- 1. This part is designed to attach a 20 or 22 AWG lead to a solder dipped pin 1.02 (0.040) in diameter.
- 2. Part may be installed with infrared or convection heating technique.

<b>tyco</b> Electronics		Raychem		Tyco Electronics Corporation 300 Constitutional Drive Menlo Park, CA 94025 USA		SOLDERSLEEVE, LEAD/ PIN TERMINATION			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.						DOCUMENT NO.: <b>D-141-56</b>			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ROU	ANGLES: N/A ROUGHNESS IN MICRON		Electronics reserves to ng at any time. Users illity of the product for	DATE: 04-Apr01		DOC ISSUE:		
DRAWN BY: M. FORONDA		CAGE CODE 06090		REPLACES: N/A	DCR NUMBER: D010067	PROD. REV.: A	SCALE: None	SIZE:	SHEET: 1 of 1

## **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

TE Connectivity: